



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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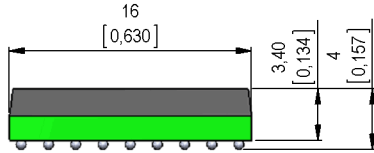


Dimensions mm[inch]

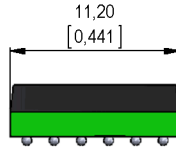
tolerances acc. to DIN ISO 2768-m
 Toleranzen gem. DIN ISO 2768-m

Isometric

Scale 1:1
 Maßstab 1:1

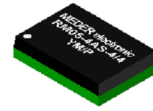


Post reflow hight



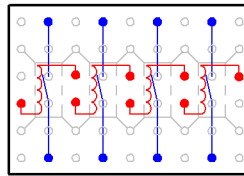
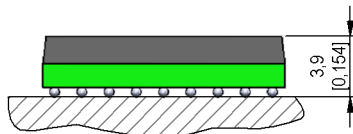
Layout

Top view
 Draufsicht

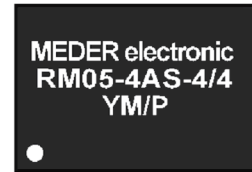


Marking

according to EN60062/factory code
 gem. EN60062/Fertigungsstätte



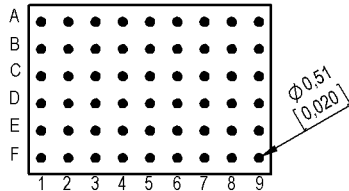
red dots = coil pins
 blue dots = switch pins
 grey dots = shield pins (all grey pins interconnected)



Recommended PCB Pad Layout

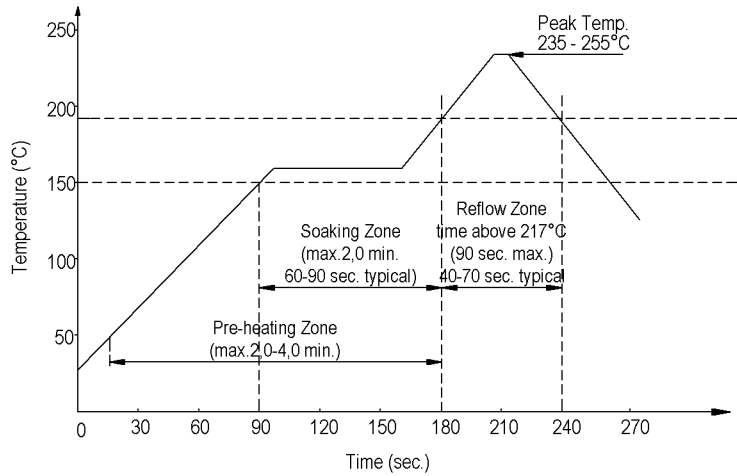
Top view / Draufsicht

Grid Spacing is 1.8mm on center



Recommended lead free reflow profile

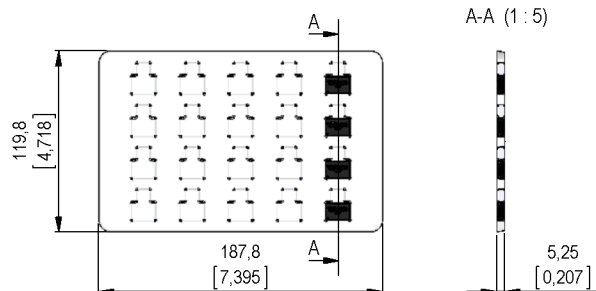
typical reflow profile for RM series for usage with
 Sn96,5 Ag3 Cu0,5



HF - Parameter

See webpage www.meder.com or ask
 your responsible Customer Service
 Einzusehen unter www.meder.com oder kontaktieren
 Sie den verantwortlichen Vertriebsmitarbeiter

Relay packaging orientation





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Item:

RM05-4AS-4/4

Coil Data at 20 °C	Conditions	Min	Typ	Max	Unit
Coil resistance		166	185	204	Ohm
Coil voltage			5		VDC
Rated power			135		mW
Pull-In voltage				3,75	VDC
Drop-Out voltage		0,5			VDC

RF Characteristics	Conditions	Min	Typ	Max	Unit
S-Parameters		Available upon request			

Contact data 80	Conditions	Min	Typ	Max	Unit
Contact-No.		80			
Contact-form		A			
Contact-material		Rhodium			
Contact-rating	Any DC combination of V & A not to exceed their individual max.'s			10	W
Switching voltage	DC or Peak AC			170	V
Switching current	DC or Peak AC			0,5	A
Carry current	DC or Peak AC			0,5	A
Contact resistance static	Measured with 40% overdrive Start Value			200	mOhm
Insulation resistance	RH <45 %, 100 V test voltage	1	10		GOhm
Breakdown voltage	according to EN 60255-5	210			VDC
Operate time incl. bounce	measured with 40% overdrive			0,6	ms
Release time	measured with no coil excitation			0,1	ms
Capacitance	@ 10 kHz above open switch		0,2		pF

Special Product Data	Conditions	Min	Typ	Max	Unit
Number of contacts		4			
Isolation voltage Coil/Contact	according to EN 60255-5	1,5			kV DC
Insulation resistance Coil/Contact	RH <45%, 200 VDC measuring voltage	10			TOhm
Capacity Coil/Contact	@ 10 kHz		0,7		pF
Case color		black			
Sealing compound		Thermoset Molding Compound			
Material connection pads		BGA solderballs D=0,025 inches, Pb free			
Reach / RoHS conformity		yes			
Magnetic Shield		yes			

Environmental data	Conditions	Min	Typ	Max	Unit
Shock	1/2 sine wave duration 11ms			50	g
Vibration	from 10 - 2000 Hz			20	g
Operating temperature		-40		85	°C
Storage temperature		-55		125	°C
Reflow Soldering Temperature				260	°C
Washability		fully sealed			

General data	Conditions	Min	Typ	Max	Unit
Packaging		4 x 5 Blister packaged			

Modifications in the sense of technical progress are reserved

Designed at: 07.12.09 Designed by: MAPODACA

Approval at: 07.12.09 Approval by: TLANE

Last Change at: 29.02.16 Last Change by: AAI

Approval at: 15.03.16 Approval by: DSTASTNY

Version: 7